

Filename: PMP2715 REV\_C\_bom.xls

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## PMP2715 REV\_C BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	22uF	Capacitor, Ceramic, 6.3V, X5R, 15%	0805	Std	TDK
1	C2	10uF	Capacitor, Ceramic, 16V, X7R, 10%	1206	C3216X7R1C106K	TDK
1	C3	470uF	PCB Receptacle for 0.020-0.032 leads	0.315 inch	16ZL470M10x12.5	Rubycon
1	C5	10nF	Capacitor, Ceramic, 10nF, 25V, X7R	0603	Std	Std
2	C6	1uF	Capacitor, Ceramic, 1uF, 16V, X7R	0603	C1608X7R1C105M	TDK
	C7	1uF	Capacitor, Ceramic, 1uF, 16V, X7R	0603	C1608X7R1C105M	TDK
1	D1	B320B	Diode, Schottky, 3-A, 20-V	SMB	B320B	Diodes Inc.
2	J1	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
	J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	L1	1.2uH	Inductor, SMT High Current, 12.4A, 7.5milliohm	0.430 x 0.410 inch	HC8LP-1R2-R	Coiltronics
1	Q1	MMBT3904	Bipolar, NPN, 40V, 200mA, 225mW	SOT23	MMBT3904LT1	On Semi
1	Q2	IRF7607	XSTR, MOSFET, N-Chan, 20V, Rds(ON) = 30 milli ohm	TSSOP8- MICRO8	IRF7607	IR
2	Q4	MMBT3906	Bipolar, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906LT1	On Semi
	Q5	MMBT3906	Bipolar, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906LT1	On Semi
1	R1	4.75	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
2	R2	221	Resistor, Chip, 1/16W, 5%	0603	Std	Std
	R3	221	Resistor, Chip, 1/16W, 5%	0603	Std	Std
1	R4	18.2k	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R5	10k	Resistor, Chip, 10K-Ohms, 1/16-W, 1%	0603	Std	Std
1	R6	13k	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R7	1.1K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R8	10K	Resistor, Chip, 1/16-W, 1%	0603	Std	Std
1	R9	51.1	Resistor, Chip, 51.1 Ohms, 1/16-W, 1%	0603	Std	Std
1	R10	475	Resistor, Chip, 1/16W, 5%	0603	Std	Std
8	TP1	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP2	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP4	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP6	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone

	TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
	TP8	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	TL5001A-Q1	IC, PWM Controller	SO8	TL5001A-Q1	TI
1		PCB	PMP2715 Rev_C PCB			

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
  2. These assemblies must be clean and free from flux and all contaminants.  
Use of no clean flux is not acceptable.
  3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
  4. Ref designators marked with an asterisk (\*\*\*) cannot be substituted.  
All other components can be substituted with equivalent MFG's components.

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